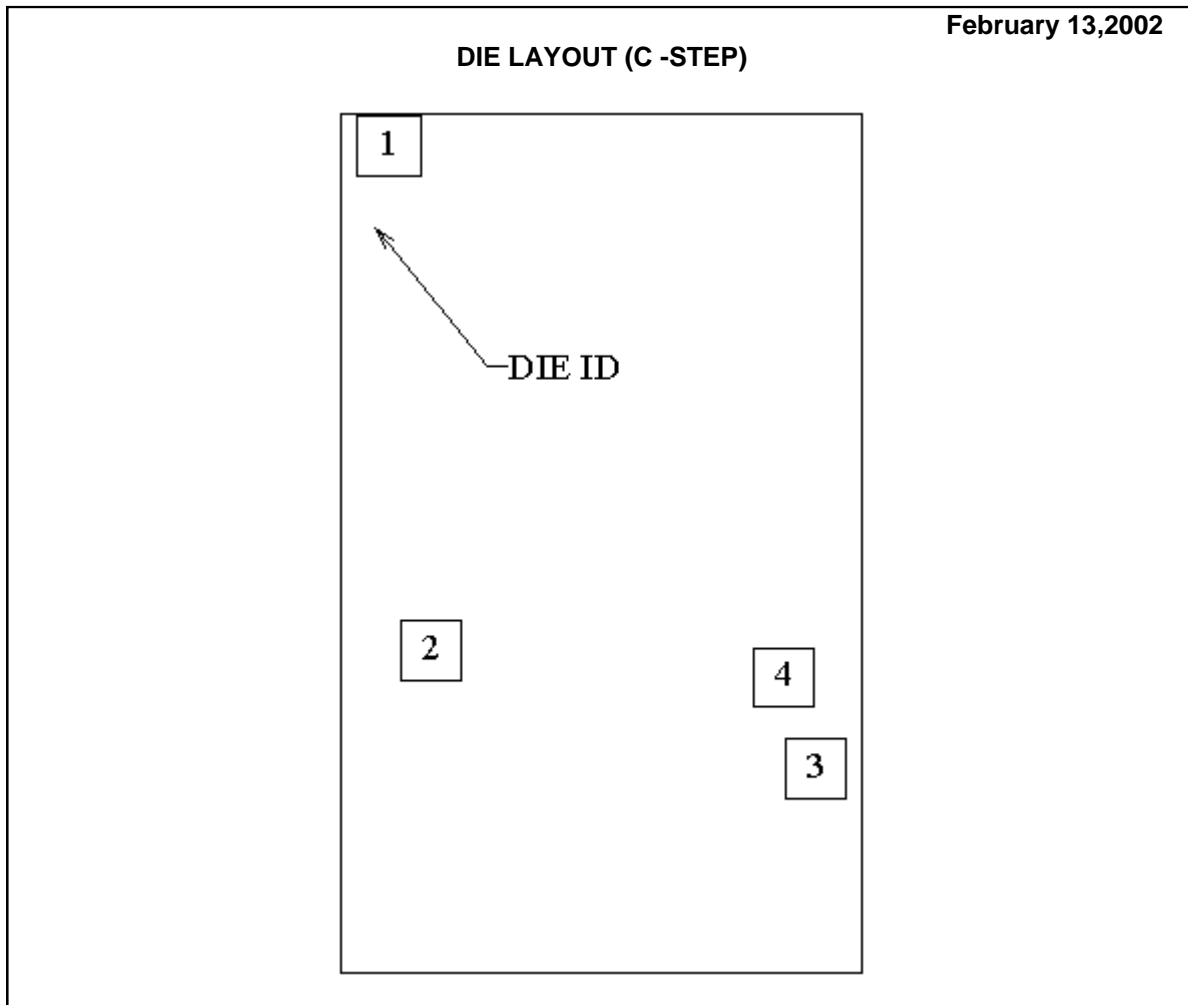


**LM317L MDA MWA  
3-TERMINAL ADJUSTABLE REGULATOR**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	317L	Bond Pad Opening Size (min)	117 $\mu$ m x 117 $\mu$ m
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1676 $\mu$ m x 1016 $\mu$ m 66mils x 40mils	Back Side Connection	VOUT
Thickness	330 $\mu$ m Nominal		
Min Pitch	1290 $\mu$ m Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.** Pads 2 & 3 require common VOUT connection.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y CORRDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
ADJ	1	-414	775	127	x	117
VOUT	2	-330	-210	117	x	119
VOUT	3	419	-439	117	x	117
VIN	4	356	-262	117	x	117

**LM317L MDA MWA**  
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